L Number	Hits	Search Text	DB	Time stamp
1	42	(chip IC die) with (power adj supply adj module)	USPAT; US-PGPUB; EPO; JPO;	2003/08/14
2	5	sasakura-takahiro.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/08/14
3	193	abe-seiichi.in.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/14 11:59
4	36	<pre>(electronic adj component) with ((power adj circuit) (power adj supply adj module))</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/14 12:00
5	441	257/777,784,723,676,684.ccls. and power and (heat adj (sink plate slug element spreader))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/14 14:00
6	5552	(power adj supply) and (open\$4 recess\$4) and (heat adj (sink plate spreader element slug))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:03
7	1998	(power adj supply) and (open\$4 recess\$4) and (heat adj (sink plate spreader element slug)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:03
9	153	(power adj supply) with (open\$4 recess\$4) and (heat adj (sink plate spreader element slug)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:05
10	28	257/737-738,675,706,711-713.ccls. and (power adj supply) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:13
11	1060	(power adj supply) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:17
12	9621	(chip IC die) with (heat adj (sink plate element slug spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:18
13	2022	(chip IC die) with (heat adj (sink plate element slug spreader)) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/14 14:20
14	17	("4042539" "4740425" "4876588" "4914551" "5022968" "5028984" "5206792" "5208103" "5218215" "5262674" "5300158" "5343073" "5346765" "5367196" "5422788" "5591034" "5608267").PN.	USPĀT	2003/08/14 14:23

	7- 46	/#5303013# #5503330# #5304030# :	MODE	2002/00/14
15	12	1 '	USPAT	2003/08/14
		"5726493" "5796038" "5854511"		14:33
		"5866943" "5886408" "5909056"		
		"5926371" "6020637" "6046499").PN.		
_	8		USPAT;	2003/08/13
		("6252299") or ("5394010")).PN.	US-PGPUB;	19:34
		(0232233 / OI (3334010 //.IN.	EPO; JPO;	13.31
1			· ·	
			DERWENT;	
			IBM_TDB	
-	81750	(power adj supply) and (chip die IC)	USPAT;	2003/08/13
			US-PGPUB;	19:36
1	1		EPO; JPO;	
		•	DERWENT;	
			IBM TDB	
<u>-</u>	637	(power adj supply) and (chip die IC) and	USPAT;	2003/08/13
		stack and seal	US-PGPUB;	19:39
		bodon and bodz	EPO; JPO;	
			DERWENT;	
1			IBM TDB	
	222	/manage and assembly and anadylah and /ahda		2002/08/12
-	337		USPAT;	2003/08/13
		die IC) and stack and seal	US-PGPUB;	19:49
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
-	6	257/777,784,723,676,684.ccls. and (power	USPAT;	2003/08/14
		adj supply adj module)	US-PGPUB;	13:46
	1	and tapped and meaning,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
	1	257/685-686,690-691.ccls. and (power adj	USPAT;	2003/08/13
-	1		US-PGPUB;	19:59
		supply adj module)		19.59
			EPO; JPO;	
	1		DERWENT;	
1			IBM_TDB	/
-	0	20030047800.URPN.	USPAT	2003/08/13
		'		19:53
-	5	257/737-738,675,706,711-713.ccls. and	USPAT;	2003/08/14
		(power adj supply adj module)	US-PGPUB;	14:08
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1_	43	257/777,784,723,676,684.ccls. and (power	USPAT;	2003/08/13
	1 13	adj circuit)	US-PGPUB;	19:59
		adj circuit,	EPO; JPO;	13.03
			DERWENT;	
		057/505 506 500 501 3	IBM_TDB	2002/09/12
-	46		USPAT;	2003/08/13
		circuit)	US-PGPUB;	19:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	55	257/737-738,675,706,711-713.ccls. and	USPAT;	2003/08/14
		(power adj circuit)	US-PGPUB;	11:45
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			DERWENT;	
			IBM TDB	1
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